



GreenMOS™

OSG55R160xZF_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Ultra-fast and robust body diode
- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

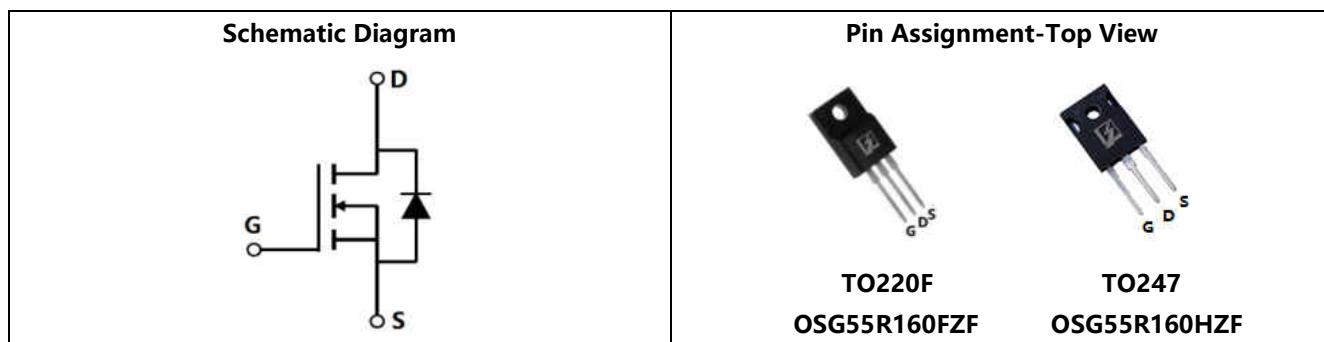
- ◆ Lighting
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar invertor

■ General Description

OSG55R160xZF uses advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and power supplies.

◆ $V_{DS, min@Tjmax}$	600 V
◆ $I_D, pulse$	69 A
◆ $R_{DS(ON)}, \text{max @ } VGS=10 \text{ V}$	160 mΩ
◆ Q_g	21.3 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	550	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25^\circ\text{C}$	I_D	23	A
Continuous drain current ¹⁾ , $T_C=100^\circ\text{C}$		14.5	
Pulsed drain current ²⁾ , $T_C=25^\circ\text{C}$	$I_{D, \text{pulse}}$	69	A
Power dissipation ³⁾ for TO247, $T_C=25^\circ\text{C}$	P_D	151	W
Power dissipation ³⁾ for TO220F, $T_C=25^\circ\text{C}$		34	
Single pulsed avalanche energy ⁵⁾	E_{AS}	250	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...440 \text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...440 \text{ V}, I_{SD} \leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO247	TO220F	
Thermal resistance, junction-case	R _{θJC}	0.82	3.7	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	550			V	V _{GS} =0 V, I _D =250 μA
		600	675			V _{GS} =0 V, I _D =250 μA, T _j =150 °C
Gate threshold voltage	V _{GS(th)}	3.0		4.5	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}		0.12	0.16	Ω	V _{GS} =10 V, I _D =11.5 A
			0.29			V _{GS} =10 V, I _D =11.5 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			10	μA	V _{DS} =550 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		1511.1		pF	V _{GS} =0 V, V _{DS} =50 V, f=100 kHz
Output capacitance	C _{oss}		145.8		pF	
Reverse transfer capacitance	C _{rss}		2.9		pF	
Turn-on delay time	t _{d(on)}		28.0		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =2 Ω, I _D =10 A
Rise time	t _r		8.8		ns	
Turn-off delay time	t _{d(off)}		37.9		ns	
Fall time	t _f		4.3		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		21.3		nC	$I_D=10\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		7.5		nC	
Gate-drain charge	Q_{gd}		7.3		nC	
Gate plateau voltage	$V_{plateau}$		6.9		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			23	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			69		
Diode forward voltage	V_{SD}			1.3	V	$I_S=23\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		122.1		ns	$V_R=400\text{V}, I_S=10\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		0.7		μC	
Peak reverse recovery current	I_{rrm}		11.0		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^{\circ}\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=25\text{ }\Omega$, $L=10\text{ mH}$, starting $T_j=25\text{ }^{\circ}\text{C}$.

■ Electrical Characteristics Diagrams

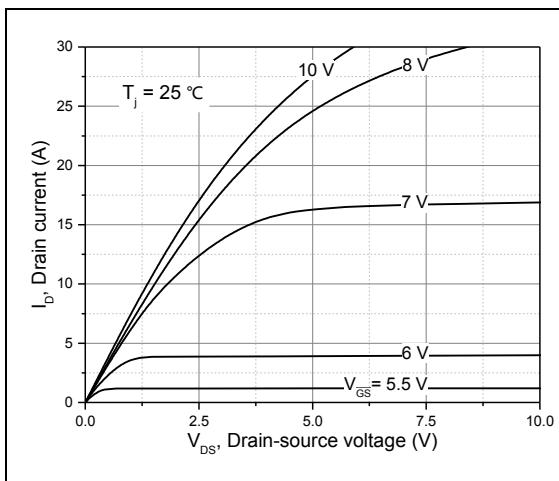


Figure 1, Typ. output characteristics

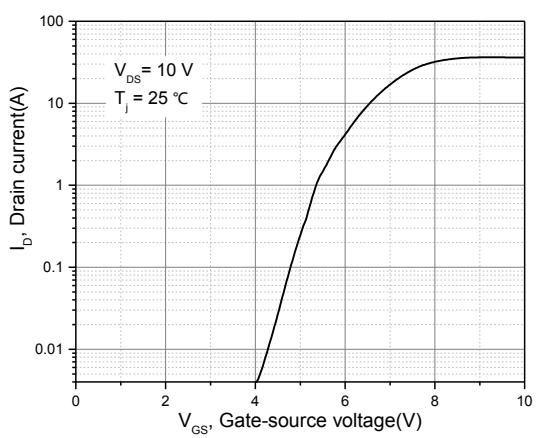


Figure 2, Typ. transfer characteristics

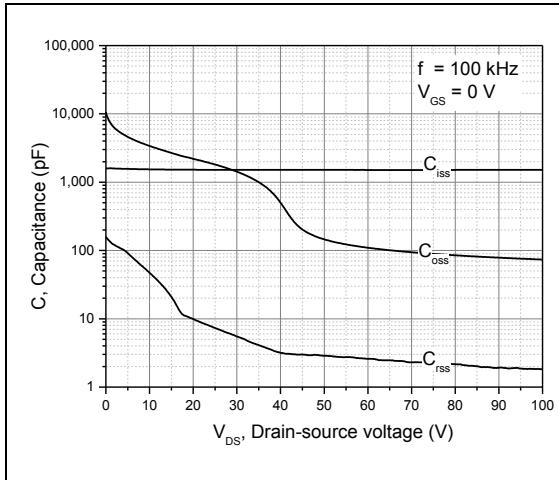


Figure 3, Typ. capacitances

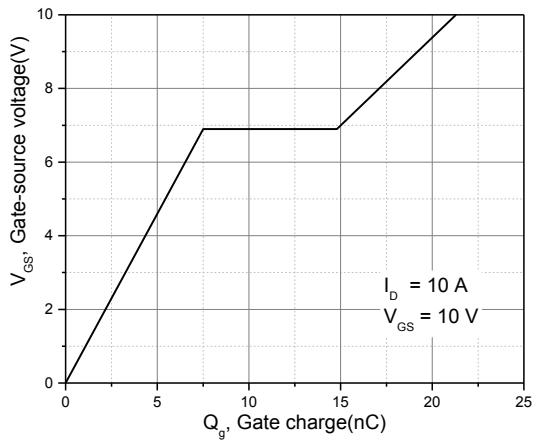


Figure 4, Typ. gate charge

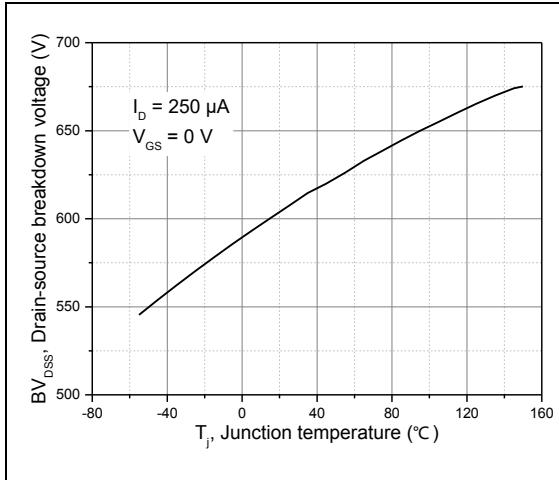


Figure 5, Drain-source breakdown voltage

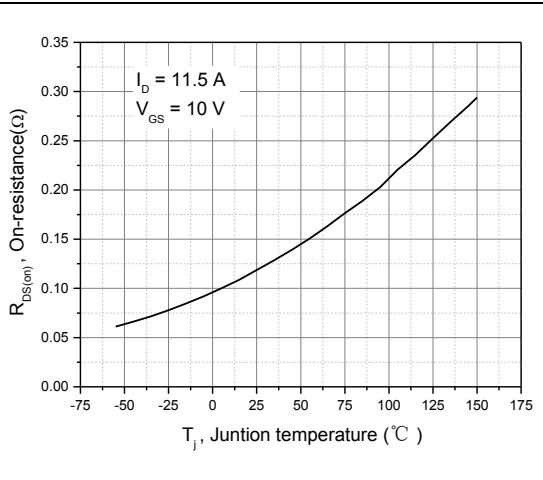


Figure 6, Drain-source on-state resistance

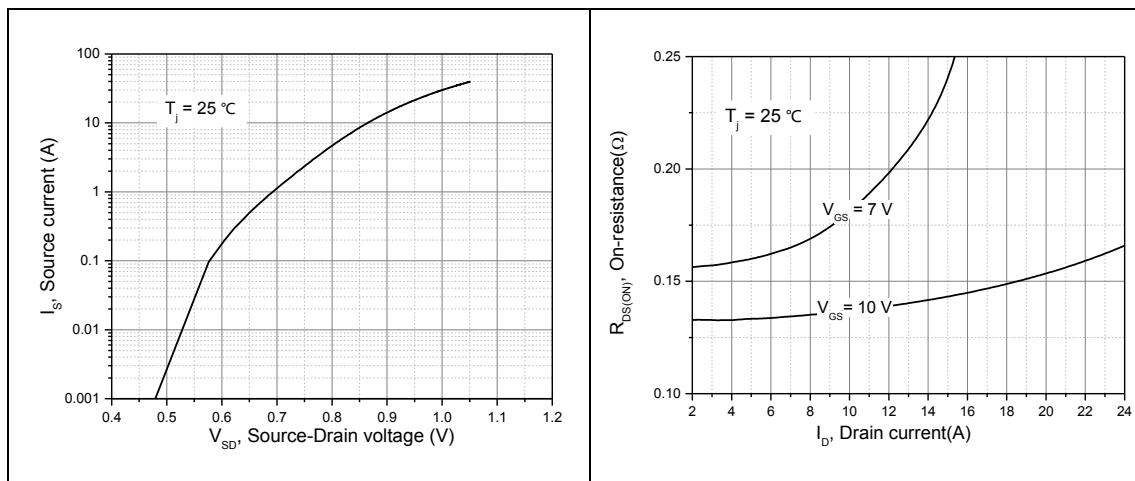


Figure 7, Forward characteristic of body diode

Figure 8, Drain-source on-state resistance

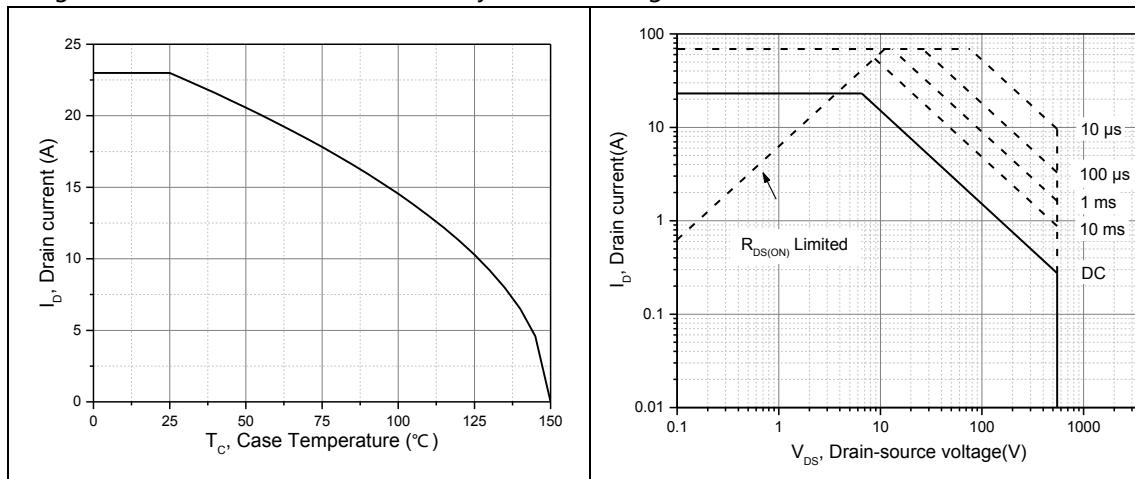


Figure 9, Drain current

Figure 10, Safe operation area for TO247

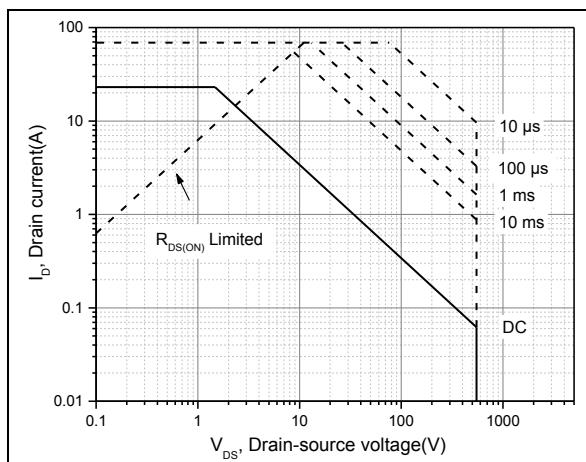
 $T_C = 25 \text{ } ^\circ\text{C}$ 

Figure 10, Safe operation area for TO220F

 $T_C = 25 \text{ } ^\circ\text{C}$

■ Test circuits and waveforms

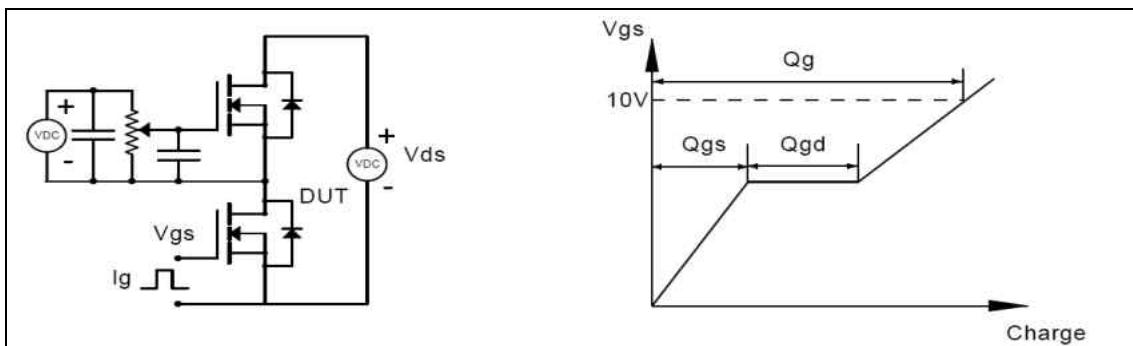


Figure 1, Gate charge test circuit & waveform

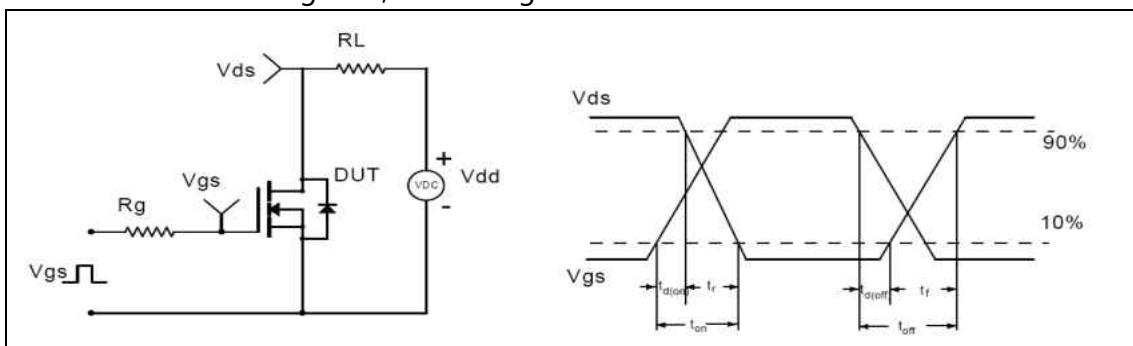


Figure 2, Switching time test circuit & waveforms

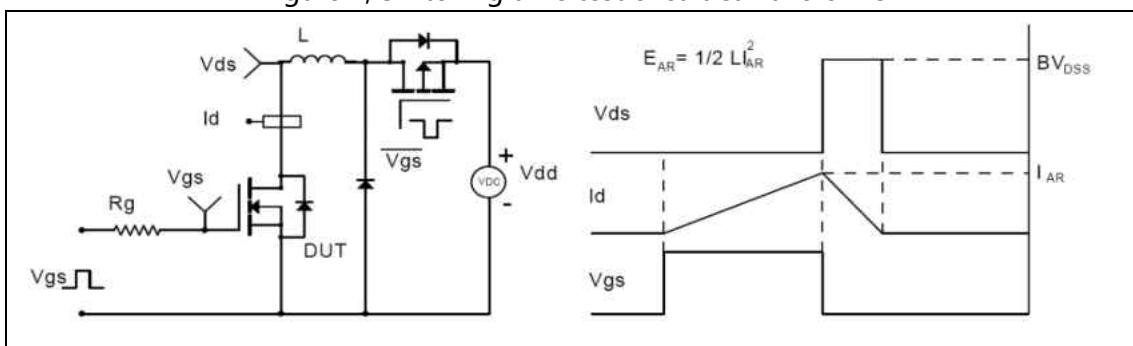


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

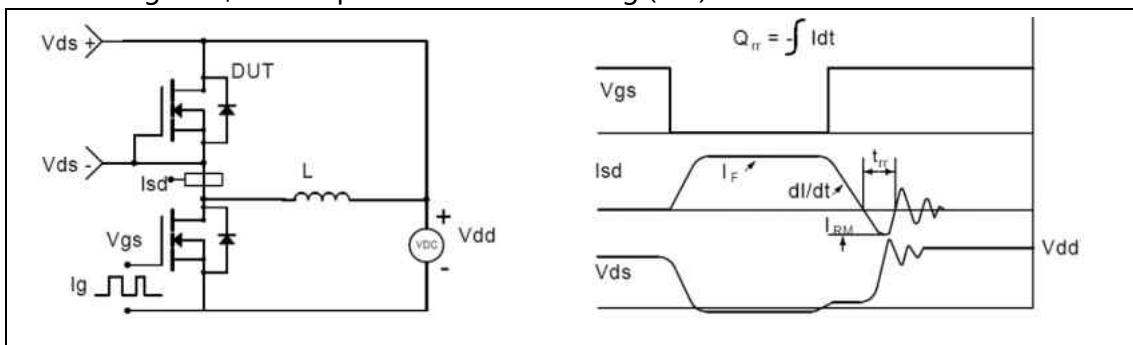
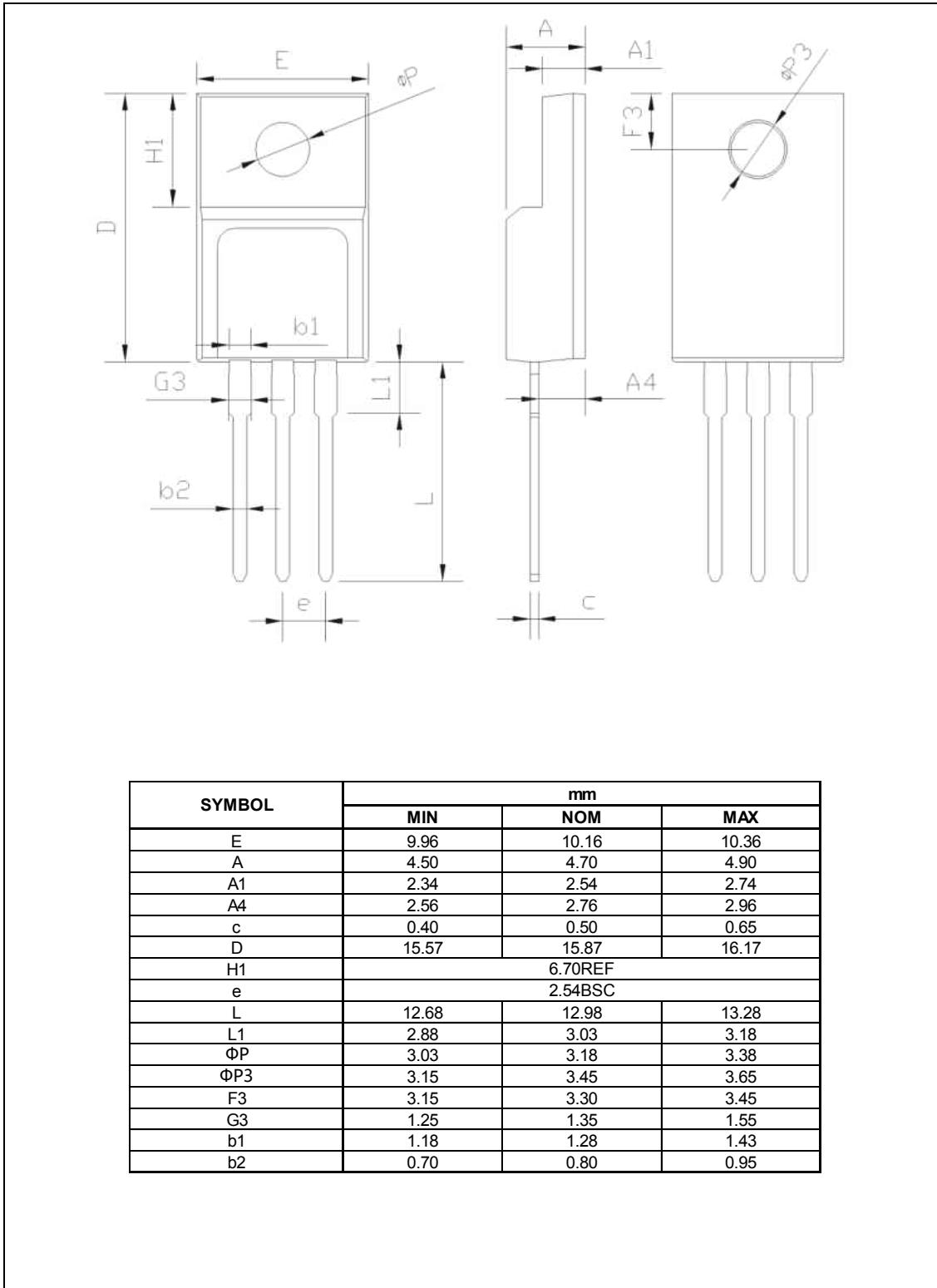


Figure 4, Diode reverse recovery test circuit & waveforms

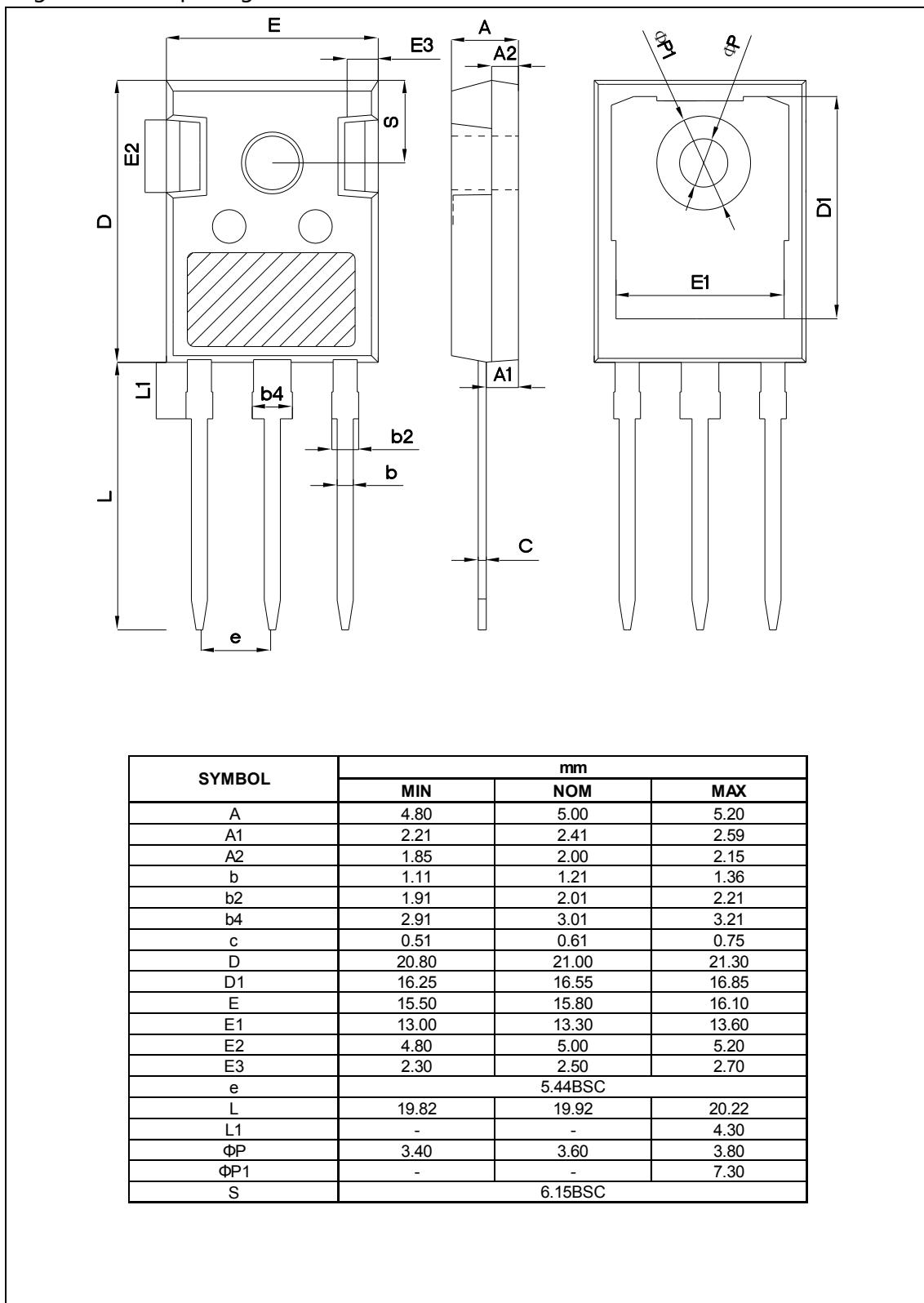
■ Package Information

Figure1, TO220F package outline dimension



■ Package Information

Figure2, TO247 package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO220F	50	20	1000	6	6000
TO247	30	11	330	6	1980

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG55R160FZF	TO220F	yes	yes	yes
OSG55R160HZF	TO247	yes	yes	yes